

QUALIFICATIONS

The solder paste BLF 08 is an RMA-paste that accords to the requirements of the MILQQ-S571e. The corrosion-, solder ball- and the wetting test as well as the slump (according to ISO, J-STD-004/005 L1) were passed. Laboratory research confirmed corrosion free residues, corresponding to the RO L0, which can remain on the board. If wetting of the PCB can occur during the use of it, even for a short term, appropriate measures against moisture have to be applied.

HANDLING

After taking out the paste, close the container tightly. Used paste should not be stored with fresh paste together. In the running working process it is of course allowed to mix in fresh paste to freshen up the old one. Different alloys and types of paste shall not be mixed. Recommended squeegee speed: 15 – 100 mm/s.

Remember! The printer is always faster than the fastest assembler in the line. The most important is that the paste rolls in front of the squeegee.

For stencil printing a paste with 90% metal content is recommended.

The cleaning of the stencil can be done with an alcoholic mixture, but the cleaning medium shall under no circumstances get in contact with the paste. **We recommend thus the SC Stencilcleaner.** The solder paste is applicable with all common reflow systems.

STORAGE

Unopened at room temperature (20°C/68°F): 6 months

Opened or at the squeegee of the printing device the maximum working time is dependant of the environmental influences to which the paste is exposed.

A storage in the refrigerator is not necessary!

Solder Chemistry order example

Paste type	Grain size	Alloy	Flux content	Jar capacity
BLF08	T3	96.5/Ag3/Cu0.5	12%	500g
BLF08	T3	96.5/Ag3.5	12%	200g

Order example according to DIN:

Solder paste SC BLF08 L-Sn96.5Ag3Cu0.5 1.2.2.C / 88 - 3 500g (packing)

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